

**IN THE CLAIMS**

Please amend the claims as follows:

1-35. (Canceled)

36. (Currently Amended) A device [for an edge bead,] comprising:

a dispenser configured to release a chemical toward [said] an edge bead; and  
a splash controller around said dispenser, physically unattached from [said] the edge bead, and configured to draw [said] the chemical toward said splash controller, wherein said splash controller is configured to generate a gas pressure around [said] the edge bead that is lower than an ambient gas pressure, and wherein said splash controller is configured to physically intercept [said] the chemical.

37. (Currently Amended) The device in claim 36, wherein [said] the splash controller is around [said] the edge bead.

38. (New) The device of claim 36, wherein the splash controller completely surrounds said dispenser.

39. (New) The device of claim 36, wherein the dispenser has a diameter smaller than a diameter of the splash controller.

40. (New) The device of claim 36, wherein said dispenser is configured to release a chemical on a first side of a wafer and a second side of the wafer toward an edge bead, wherein the splash controller completely surrounds said dispenser.

41. (New) A device comprising:

a dispenser configured to release a chemical toward an edge bead on a semiconductor substrate; and

a splash controller including a vacuum port, wherein the vacuum port completely surrounds the dispenser, wherein the vacuum port is configured to generate a gas pressure around the edge

bead and the dispenser, the generated gas pressure being sufficiently lower than an ambient gas pressure to draw the chemical toward the splash controller, wherein the dispenser has a smaller diameter than the vacuum port, and wherein the splash controller is configured to physically intercept the chemical.